



Advances in Tangible and Embodied Interaction for Virtual and Augmented Reality

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Deadline for manuscript
submissions:

closed (15 January 2023)

Message from the Guest Editors

For this Special Issue, we are interested in gathering research that bridges atoms and bits in virtual and augmented environments. Basic research papers that demonstrate new interaction technologies or techniques, descriptions of applications that use tangibles in VR/AR in any domain, and survey papers that can help structure and systematize current knowledge on this area are all suitable. Topics of interest include, but are not limited to:

- Technologies for object detection/recognition in AR
- Interaction techniques that use tangibles/embodied interactions
- Haptic systems and interactions for VR/AR
- Authoring systems
- Programming libraries, toolkits, and frameworks
- Applications in cultural heritage, medicine, rehabilitation, gaming, entertainment, teaching, training, visualization, etc.
- Design methodologies
- Evaluation methodologies





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Message from the Editor-in-Chief

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